

Please note that Cypress is an Infineon Technologies Company.

The document following this cover page is marked as “Cypress” document as this is the company that originally developed the product. Please note that Infineon will continue to offer the product to new and existing customers as part of the Infineon product portfolio.

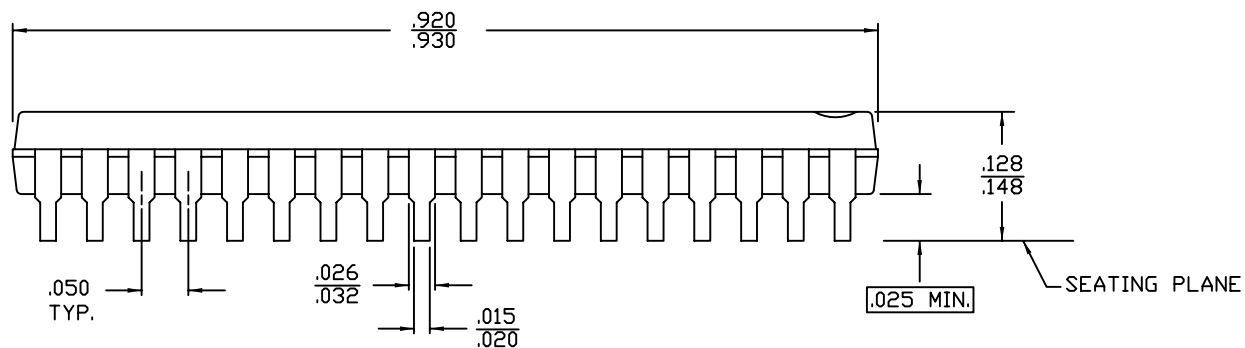
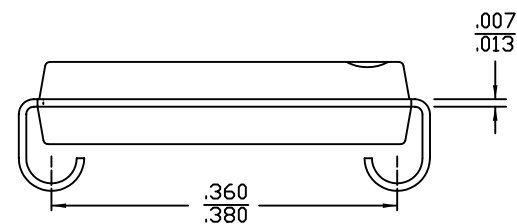
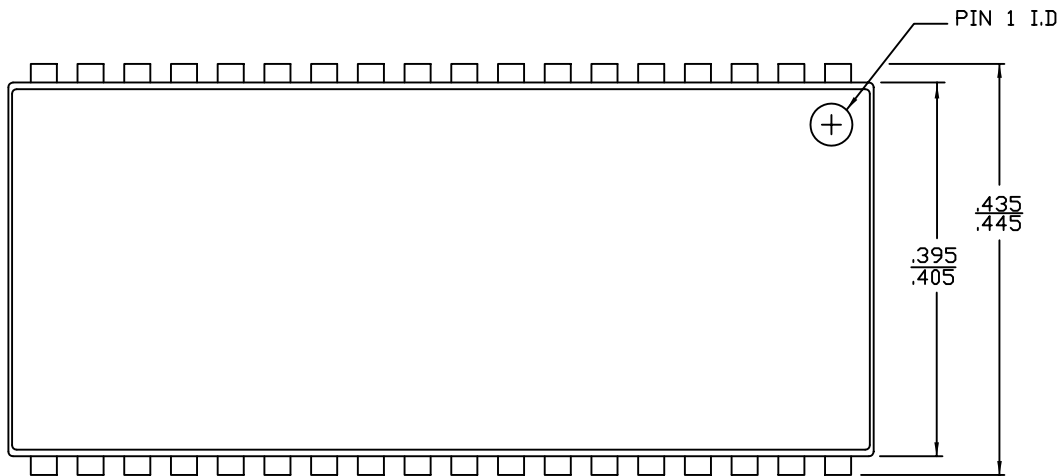
Continuity of document content

The fact that Infineon offers the following product as part of the Infineon product portfolio does not lead to any changes to this document. Future revisions will occur when appropriate, and any changes will be set out on the document history page.


Continuity of ordering part numbers

Infineon continues to support existing part numbers. Please continue to use the ordering part numbers listed in the datasheet for ordering.

36 Lead (400 MIL) Molded SOJ V36




DIMENSIONS IN INCHES MIN.
MAX.

 CYPRESS Company Confidential	
TITLE PACKAGE OUTLINE, 36L SOJ V36.4 (MOLDED)	
SPEC NO. 51-85090	REV *G
SCALE	SHEET 1 OF 2

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PACKAGE
CODE(S)

Rev	ECN No.	Orig. of change	Description of Change
**	48093	—	NEW RELEASE
*A	57335	—	CHG. PKG. THICK DIM.
*B	64703	—	PKG. THICKNESS OPTION
*C	498426	TSV	CHANGE OVERALL PACKAGE THICKNES/CHANGE STANDOFF MIN:HEIGHT
*D	2779863	ROWI	CHANGED TO STANDARD DRAWING FORMAT CHANGED TITLE FROM 36.4 SOJ PKG. OUTL.—DATA BOOK TO PACKAGE OUTLINE, 36L SOJ V36.4 (MOLDED)
*E	3022278	TSV	ADD GENERAL TOLERANCE 0.05 TO THE TITLE HEADER
*F	3373659	AGM	Update spec for sunset review, no changed
*G	4709311	ROWI	SUNSET REVIEW, CHANGED DRAWING TEMPLATE.

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